

L Number	Hits	Search Text	DB	Time stamp
1	0	sacrificial adj dielectric adj planarization adj layer	USPAT	2004/11/02 18:01
2	713	microelectronic and trench and (sacrificial adj layer) and metal simultaneously and removing and substantially and (hard adj mask)	USPAT	2004/11/02 18:03
3	244	microelectronic and trench and (sacrificial adj layer) and metal simultaneously and removing and substantially and (hard adj mask) and dishing	USPAT	2004/11/02 18:04
4	83	(microelectronic and trench and (sacrificial adj layer) and metal simultaneously and removing and substantially and (hard adj mask) and dishing) and (without adj substantially adj removing adjs hard adj mask)	USPAT	2004/11/02 18:07
5	83	(microelectronic and trench and (sacrificial adj layer) and metal simultaneously and removing and substantially and (hard adj mask) and dishing) and (dishing adj7 without adj substantially adj removing adjs hard adj mask)	USPAT	2004/11/02 18:06
6	0	(microelectronic and trench and (sacrificial adj layer) and metal simultaneously and removing and substantially and (hard adj mask) and dishing) and (without adj substantially adj removing adj hard adj mask)	USPAT	2004/11/02 18:07
7	0	((microelectronic and trench and (sacrificial adj layer) and metal simultaneously and removing and substantially and (hard adj mask) and dishing) and (without adj substantially adj removing adjs hard adj mask)) and (without adj substantially adj removing adj hard adj mask)	USPAT	2004/11/02 18:07
8	0	(microelectronic and trench and (sacrificial adj layer) and metal simultaneously and removing and substantially and (hard adj mask)) and (without adj substantially adj removing adj hard adj mask)	USPAT	2004/11/02 18:08
9	0	microelectronic and trench and dishing and (without adj substantially adj removing adj hard adj mask)	USPAT	2004/11/02 18:08
10	13	microelectronic and trench and dishing and (hard aaj mask) and metal and sacrificial	USPAT	2004/11/02 18:09
11	13	(microelectronic and trench and dishing and (hard aaj mask) and metal and sacrificial) and (substantially or without or removing or simultaneously or surface or conductive or metal or trench or dishing or depth or thickness or removal or rate or dielectric or IDL)	USPAT	2004/11/02 18:14
12	13	(microelectronic and trench and dishing and (hard aaj mask) and metal and sacrificial) and (substantially or without or removing or simultaneously or surface or conductive or metal or trench or dishing or depth or thickness or removal or rate or dielectric or IDL or CVD or CMP)	USPAT	2004/11/02 18:43
13	1	("6297554").PN.	USPAT	2004/11/02 18:41
14	1	((("6297554").PN.) and (substantially or without or removing or simultaneously or surface or conductive or metal or trench or dishing or depth or thickness or removal or rate or dielectric or IDL or CVD or CMP)	USPAT	2004/11/02 18:44
15	3054	438/637	USPAT	2004/11/02 18:51
16	2726	438/622	USPAT	2004/11/02 18:51
17	1515	438/627	USPAT	2004/11/02 18:51
18	1439	438/643	USPAT	2004/11/02 18:51
19	1135	438/680	USPAT	2004/11/02 18:51
20	559	438/681	USPAT	2004/11/02 18:51
21	704	438/696	USPAT	2004/11/02 18:51
22	1417	438/700	USPAT	2004/11/02 18:52
23	1000	438/689	USPAT	2004/11/02 18:52
24	1338	438/691	USPAT	2004/11/02 18:52
25	619	438/782	USPAT	2004/11/02 18:52
26	1035	438/683	USPAT	2004/11/02 18:52
27	1699	438/687	USPAT	2004/11/02 18:52
28	377	438/311	USPAT	2004/11/02 18:53

Search History 11/2/04 6:53:14 PM Page 1

11/2/04